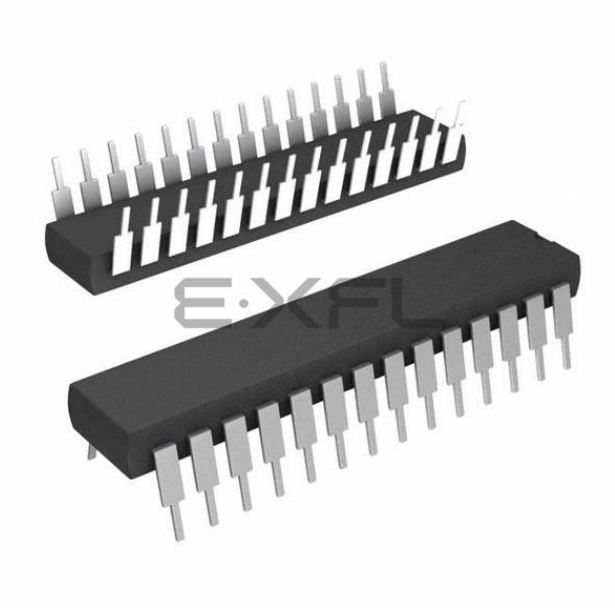

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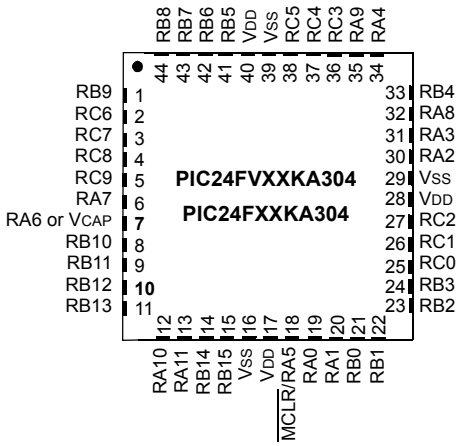
Applications of "Embedded - Microcontrollers"

Details	
Product Status	Active
Core Processor	PIC
Core Size	16-Bit
Speed	32MHz
Connectivity	I²C, IrDA, LINbus, SPI, UART/USART
Peripherals	Brown-out Detect/Reset, HLVD, POR, PWM, WDT
Number of I/O	24
Program Memory Size	32KB (11K x 24)
Program Memory Type	FLASH
EEPROM Size	512 x 8
RAM Size	2K x 8
Voltage - Supply (Vcc/Vdd)	1.8V ~ 3.6V
Data Converters	A/D 13x12b
Oscillator Type	Internal
Operating Temperature	-40°C ~ 125°C (TA)
Mounting Type	Through Hole
Package / Case	28-DIP (0.300", 7.62mm)
Supplier Device Package	28-SPDIP
Purchase URL	https://www.e-xfl.com/product-detail/microchip-technology/pic24f32ka302-e-sp

Pin Diagrams

44-Pin TQFP/QFN(1,2,3)



Pin	Pin Features	
	PIC24FVXXKA304	PIC24FXXKA304
1	SDA1/T1CK/U1RTS/CTED4/CN21/RB9	SDA1/T1CK/U1RTS/CTED4/CN21/RB9
2	U1RX/CN18/RC6	U1RX/CN18/RC6
3	U1TX/CN17/RC7	U1TX/CN17/RC7
4	OC2/CN20/RC8	OC2/CN20/RC8
5	IC2/CTED7/CN19/RC9	IC2/CTED7/CN19/RC9
6	IC1/CTED3/CN9/RA7	IC1/CTED3/CN9/RA7
7	**VCAP**	**C2OUT/OC1/CTED1/INT2/CN8/RA6**
8	PGED2/SDI1/CTED11/CN16/RB10	PGED2/SDI1/CTED11/CN16/RB10
9	PGEC2/SCK1/CTED9/CN15/RB11	PGEC2/SCK1/CTED9/CN15/RB11
10	**AN12/HLVDIN/CTED2/INT2/CN14/RB12**	**AN12/HLVDIN/CTED2/CN14/RB12**
11	AN11/SDO1/CTPLS/CN13/RB13	AN11/SDO1/CTPLS/CN13/RB13
12	OC3/CN35/RA10	OC3/CN35/RA10
13	IC3/CTED8/CN36/RA11	IC3/CTED8/CN36/RA11
14	CVREF/AN10/C3INB/RTCC/C1OUT/OCFA/CTED5/INT1/CN12/RB14	CVREF/AN10/C3INB/RTCC/C1OUT/OCFA/CTED5/INT1/CN12/RB14
15	AN9/C3INA/T3CK/T2CK/REFO/SS1/CTED6/CN11/RB15	AN9/C3INA/T3CK/T2CK/REFO/SS1/CTED6/CN11/RB15
16	VSS/AVSS	VSS/AVSS
17	VDD/AVDD	VDD/AVDD
18	MCLR/VPP/RA5	MCLR/VPP/RA5
19	VREF+/CVREF+/AN0/C3INC/CTED1/CN2/RA0	VREF+/CVREF+/AN0/C3INC/CN2/RA0
20	CVREF-/VREF-/AN1/CN3/RA1	CVREF-/VREF-/AN1/CN3/RA1
21	PGED1/AN2/ULPWU/CTCMP/C1IND/C2INB/C3IND/U2TX/CN4/RB0	PGED1/AN2/ULPWU/CTCMP/C1IND/C2INB/C3IND/U2TX/CN4/RB0
22	PGEC1/AN3/C1INC/C2INA/U2RX/CTED12/CN5/RB1	PGEC1/AN3/C1INC/C2INA/U2RX/CTED12/CN5/RB1
23	AN4/C1INB/C2IND/SDA2/T5CK/T4CK/CTED13/CN6/RB2	AN4/C1INB/C2IND/SDA2/T5CK/T4CK/CTED13/CN6/RB2
24	AN5/C1INA/C2INC/SCL2/CN7/RB3	AN5/C1INA/C2INC/SCL2/CN7/RB3
25	AN6/CN32/RC0	AN6/CN32/RC0
26	AN7/CN31/RC1	AN7/CN31/RC1
27	AN8/CN10/RC2	AN8/CN10/RC2
28	VDD	VDD
29	VSS	VSS
30	OSCI/AN13/CLKI/CN30/RA2	OSCI/AN13/CLKI/CN30/RA2
31	OSCO/AN14/CLKO/CN29/RA3	OSCO/AN14/CLKO/CN29/RA3
32	OCFB/CN33/RA8	OCFB/CN33/RA8
33	SOSCI/AN15/U2RTS/CN1/RB4	SOSCI/AN15/U2RTS/CN1/RB4
34	SOSCO/SCLKI/U2CTS/CN0/RA4	SOSCO/SCLKI/U2CTS/CN0/RA4
35	SS2/CN34/RA9	SS2/CN34/RA9
36	SDI2/CN28/RC3	SDI2/CN28/RC3
37	SDO2/CN25/RC4	SDO2/CN25/RC4
38	SCK2/CN26/RC5	SCK2/CN26/RC5
39	VSS	VSS
40	VDD	VDD
41	PGED3/ASDA1(2)/CN27/RB5	PGED3/ASDA1(2)/CN27/RB5
42	PGEC3/ASCL1(2)/CN24/RB6	PGEC3/ASCL1(2)/CN24/RB6
43	C2OUT/OC1/INT0/CN23/RB7	INT0/CN23/RB7
44	SCL1/U1CTS/C3OUT/CTED10/CN22/RB8	SCL1/U1CTS/C3OUT/CTED10/CN22/RB8

Legend: Pin numbers in **bold** indicate pin function differences between PIC24FV and PIC24F devices.

Note 1: Exposed pad on underside of device is connected to VSS.

2: Alternative multiplexing for SDA1 (ASDA1) and SCL1 (ASCL1) when the I2CSEL Configuration bit is set.

3: PIC24F32KA304 device pins have a maximum voltage of 3.6V and are not 5V tolerant.

4.2 Data Address Space

The PIC24F core has a separate, 16-bit wide data memory space, addressable as a single linear range. The data space is accessed using two Address Generation Units (AGUs), one each for read and write operations. The data space memory map is shown in Figure 4-3.

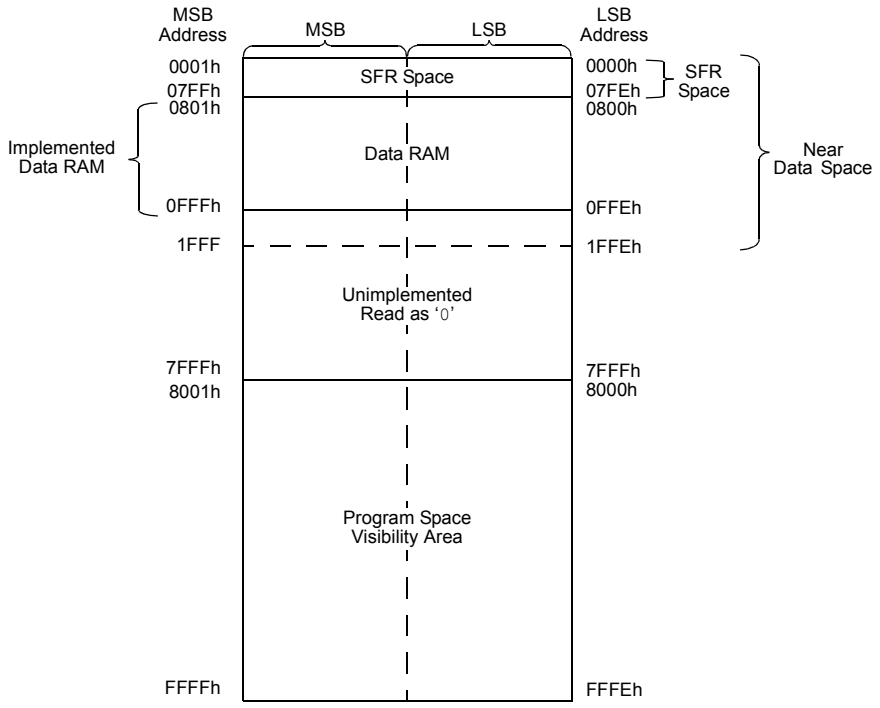
All Effective Addresses (EAs) in the data memory space are 16 bits wide and point to bytes within the data space. This gives a data space address range of 64 Kbytes or 32K words. The lower half of the data memory space (that is, when EA<15> = 0) is used for implemented memory addresses, while the upper half (EA<15> = 1) is reserved for the Program Space Visibility (PSV) area (see **Section 4.3.3 "Reading Data From Program Memory Using Program Space Visibility"**).

PIC24FV32KA304 family devices implement a total of 1024 words of data memory. If an EA points to a location outside of this area, an all zero word or byte will be returned.

4.2.1 DATA SPACE WIDTH

The data memory space is organized in byte-addressable, 16-bit wide blocks. Data is aligned in data memory and registers as 16-bit words, but all the data space EAs resolve to bytes. The Least Significant Bytes (LSBs) of each word have even addresses, while the Most Significant Bytes (MSBs) have odd addresses.

FIGURE 4-3: DATA SPACE MEMORY MAP FOR PIC24FV32KA304 FAMILY DEVICES



Note: Data memory areas are not shown to scale.

REGISTER 8-16: IEC5: INTERRUPT ENABLE CONTROL REGISTER 5

U-0	U-0	U-0	U-0	U-0	U-0	U-0	U-0
—	—	—	—	—	—	—	—
bit 15							bit 8

U-0	U-0	U-0	U-0	U-0	U-0	U-0	R/W-0
—	—	—	—	—	—	—	ULPWUIE
bit 7							bit 0

Legend:			
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as '0'	
-n = Value at POR	'1' = Bit is set	'0' = Bit is cleared	x = Bit is unknown

bit 15-1 **Unimplemented:** Read as '0'

bit 0 **ULPWUIE:** Ultra Low-Power Wake-up Interrupt Enable Bit
1 = Interrupt request is enabled
0 = Interrupt request is not enabled

The following code sequence for a clock switch is recommended:

1. Disable interrupts during the OSCCON register unlock and write sequence.
2. Execute the unlock sequence for the OSCCON high byte by writing 78h and 9Ah to OSCCON<15:8>, in two back-to-back instructions.
3. Write new oscillator source to the NOSCx bits in the instruction immediately following the unlock sequence.
4. Execute the unlock sequence for the OSCCON low byte by writing 46h and 57h to OSCCON<7:0>, in two back-to-back instructions.
5. Set the OSWEN bit in the instruction immediately following the unlock sequence.
6. Continue to execute code that is not clock-sensitive (optional).
7. Invoke an appropriate amount of software delay (cycle counting) to allow the selected oscillator and/or PLL to start and stabilize.
8. Check to see if OSWEN is '0'. If it is, the switch was successful. If OSWEN is still set, then check the LOCK bit to determine the cause of failure.

The core sequence for unlocking the OSCCON register and initiating a clock switch is shown in Example 9-1.

EXAMPLE 9-1: BASIC CODE SEQUENCE FOR CLOCK SWITCHING

```
;Place the new oscillator selection in W0
;OSCCONH (high byte) Unlock Sequence
MOV         #OSCCONH, w1
MOV         #0x78, w2
MOV         #0x9A, w3
MOV.b       w2, [w1]
MOV.b       w3, [w1]
;Set new oscillator selection
MOV.b       WREG, OSCCONH
;OSCCONL (low byte) unlock sequence
MOV         #OSCCONL, w1
MOV         #0x46, w2
MOV         #0x57, w3
MOV.b       w2, [w1]
MOV.b       w3, [w1]
;Start oscillator switch operation
BSET        OSCCON,#0
```

9.5 Reference Clock Output

In addition to the CLKO output (FOSC/2) available in certain oscillator modes, the device clock in the PIC24FV32KA304 family devices can also be configured to provide a reference clock output signal to a port pin. This feature is available in all oscillator configurations and allows the user to select a greater range of clock submultiples to drive external devices in the application.

This reference clock output is controlled by the REFOCON register (Register 9-4). Setting the ROEN bit (REFOCON<15>) makes the clock signal available on the REFO pin. The RODIVx bits (REFOCON<11:8>) enable the selection of 16 different clock divider options.

The ROSSLP and ROSEL bits (REFOCON<13:12>) control the availability of the reference output during Sleep mode. The ROSEL bit determines if the oscillator on OSC1 and OSC2, or the current system clock source, is used for the reference clock output. The ROSSLP bit determines if the reference source is available on REFO when the device is in Sleep mode.

To use the reference clock output in Sleep mode, both the ROSSLP and ROSEL bits must be set. The device clock must also be configured for one of the primary modes (EC, HS or XT); otherwise, if the ROSEL bit is not also set, the oscillator on OSC1 and OSC2 will be powered down when the device enters Sleep mode. Clearing the ROSEL bit allows the reference output frequency to change as the system clock changes during any clock switches.

REGISTER 10-2: DSWAKE: DEEP SLEEP WAKE-UP SOURCE REGISTER(1)

U-0	U-0	U-0	U-0	U-0	U-0	U-0	R/W-0, HS
—	—	—	—	—	—	—	DSINT0
bit 15							bit 8

R/W-0, HS	U-0	U-0	R/W-0, HS	R/W-0, HS	R/W-0, HS	U-0	R/W-0, HS
DSFLT	—	—	DSWDT	DSRTCC	DSMCLR	—	DSPOR(2,3)
bit 7							bit 0

Legend:	HS = Hardware Settable bit		
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as '0'	
-n = Value at POR	'1' = Bit is set	'0' = Bit is cleared	x = Bit is unknown

bit 15-9 **Unimplemented:** Read as '0'

bit 8 **DSINT0:** Deep Sleep Interrupt-on-Change bit
1 = Interrupt-on-change was asserted during Deep Sleep
0 = Interrupt-on-change was not asserted during Deep Sleep

bit 7 **DSFLT:** Deep Sleep Fault Detect bit
1 = A Fault occurred during Deep Sleep and some Deep Sleep configuration settings may have been corrupted
0 = No Fault was detected during Deep Sleep

bit 6-5 **Unimplemented:** Read as '0'

bit 4 **DSWDT:** Deep Sleep Watchdog Timer Time-out bit
1 = The Deep Sleep Watchdog Timer timed out during Deep Sleep
0 = The Deep Sleep Watchdog Timer did not time out during Deep Sleep

bit 3 **DSRTCC:** Deep Sleep Real-Time Clock and Calendar (RTCC) Alarm bit
1 = The Real-Time Clock and Calendar triggered an alarm during Deep Sleep
0 = The Real-Time Clock and Calendar did not trigger an alarm during Deep Sleep

bit 2 **DSMCLR:** Deep Sleep $\overline{\text{MCLR}}$ Event bit
1 = The $\overline{\text{MCLR}}$ pin was active and was asserted during Deep Sleep
0 = The $\overline{\text{MCLR}}$ pin was not active, or was active, but not asserted during Deep Sleep

bit 1 **Unimplemented:** Read as '0'

bit 0 **DSPOR:** Deep Sleep Power-on Reset Event bit(2,3)
1 = The VDD supply POR circuit was active and a POR event was detected
0 = The VDD supply POR circuit was not active, or was active, but did not detect a POR event

Note 1: All register bits are cleared when the DSEN (DSCON<15>) bit is set.

2: All register bits are reset only in the case of a POR event outside of Deep Sleep mode, except bit, DSPOR, which does not reset on a POR event that is caused due to a Deep Sleep exit.

3: Unlike the other bits in this register, this bit can be set outside of Deep Sleep.

14.1.2 CASCADED (32-BIT) MODE

By default, each module operates independently with its own 16-bit timer. To increase resolution, adjacent even and odd modules can be configured to function as a single 32-bit module. (For example, Modules 1 and 2 are paired, as are Modules 3 and 4, and so on.) The odd numbered module (ICx) provides the Least Significant 16 bits of the 32-bit register pairs, and the even numbered module (ICy) provides the Most Significant 16 bits. Wraparounds of the ICx registers cause an increment of their corresponding ICy registers.

Cascaded operation is configured in hardware by setting the IC32 bit (ICxCON2<8>) for both modules.

14.2 Capture Operations

The input capture module can be configured to capture timer values and generate interrupts on rising edges on ICx or all transitions on ICx. Captures can be configured to occur on all rising edges or just some (every 4th or 16th). Interrupts can be independently configured to generate on each event or a subset of events.

To set up the module for capture operations:

1. If Synchronous mode is to be used, disable the Sync source before proceeding.
2. Make sure that any previous data has been removed from the FIFO by reading ICxBUF until the ICBNE bit (ICxCON1<3>) is cleared.
3. Set the SYNCSELx bits (ICxCON2<4:0>) to the desired Sync/trigger source.
4. Set the ICTSELx bits (ICxCON1<12:10>) for the desired clock source. If the desired clock source is running, set the ICTSELx bits before the input capture module is enabled, for proper synchronization with the desired clock source.
5. Set the ICIx bits (ICxCON1<6:5>) to the desired interrupt frequency.
6. Select Synchronous or Trigger mode operation:
   a) Check that the SYNCSELx bits are not set to '00000'.
   b) For Synchronous mode, clear the ICTRIG bit (ICxCON2<7>).
   c) For Trigger mode, set ICTRIG and clear the TRIGSTAT bit (ICxCON2<6>).
7. Set the ICMx bits (ICxCON1<2:0>) to the desired operational mode.
8. Enable the selected Sync/trigger source.

For 32-bit cascaded operations, the setup procedure is slightly different:

1. Set the IC32 bits for both modules (ICyCON2<8> and (ICxCON2<8>), enabling the even numbered module first. This ensures the modules will start functioning in unison.
2. Set the ICTSELx and SYNCSELx bits for both modules to select the same Sync/trigger and time base source. Set the even module first, then the odd module. Both modules must use the same ICTSELx and SYNCSELx bit settings.
3. Clear the ICTRIG bit of the even module (ICyCON2<7>). This forces the module to run in Synchronous mode with the odd module, regardless of its trigger setting.
4. Use the odd module's ICIx bits (ICxCON1<6:5>) to the desired interrupt frequency.
5. Use the ICTRIG bit of the odd module (ICxCON2<7>) to configure Trigger or Synchronous mode operation.

Note:	For Synchronous mode operation, enable the Sync source as the last step. Both input capture modules are held in Reset until the Sync source is enabled.

6. Use the ICMx bits of the odd module (ICxCON1<2:0>) to set the desired capture mode.

The module is ready to capture events when the time base and the Sync/trigger source are enabled. When the ICBNE bit (ICxCON1<3>) becomes set, at least one capture value is available in the FIFO. Read input capture values from the FIFO until the ICBNE clears to '0'.

For 32-bit operation, read both the ICxBUF and ICyBUF for the full 32-bit timer value (ICxBUF for the lsw, ICyBUF for the msw). At least one capture value is available in the FIFO buffer when the odd module's ICBNE bit (ICxCON1<3>) becomes set. Continue to read the buffer registers until ICBNE is cleared (performed automatically by hardware).

EQUATION 16-1: RELATIONSHIP BETWEEN DEVICE AND SPIx CLOCK SPEED(1)

$$FSCK = \frac{FCY}{\text{Primary Prescaler} * \text{Secondary Prescaler}}$$

Note 1: Based on FCY = FOSC/2; Doze mode and PLL are disabled.

TABLE 16-1: SAMPLE SCKx FREQUENCIES(1,2)

FCY = 16 MHz		Secondary Prescaler Settings				
		1:1	2:1	4:1	6:1	8:1
Primary Prescaler Settings	1:1	Invalid	8000	4000	2667	2000
	4:1	4000	2000	1000	667	500
	16:1	1000	500	250	167	125
	64:1	250	125	63	42	31
FCY = 5 MHz						
Primary Prescaler Settings	1:1	5000	2500	1250	833	625
	4:1	1250	625	313	208	156
	16:1	313	156	78	52	39
	64:1	78	39	20	13	10

Note 1: Based on FCY = FOSC/2; Doze mode and PLL are disabled.

2: SCKx frequencies are indicated in kHz.

NOTES:

20.0 32-BIT PROGRAMMABLE CYCLIC REDUNDANCY CHECK (CRC) GENERATOR

Note: This data sheet summarizes the features of this group of PIC24F devices. It is not intended to be a comprehensive reference source. For more information, refer to the *"PIC24F Family Reference Manual"*, **Section 41. "32-Bit Programmable Cyclic Redundancy Check (CRC)"** (DS39729).

The programmable CRC generator provides a hardware implemented method of quickly generating checksums for various networking and security applications. It offers the following features:

- User-programmable CRC polynomial equation, up to 32 bits
- Programmable shift direction (little or big-endian)
- Independent data and polynomial lengths
- Configurable interrupt output
- Data FIFO

A simplified block diagram of the CRC generator is shown in Figure 20-1. A simple version of the CRC shift engine is shown in Figure 20-2.

FIGURE 20-1: CRC BLOCK DIAGRAM

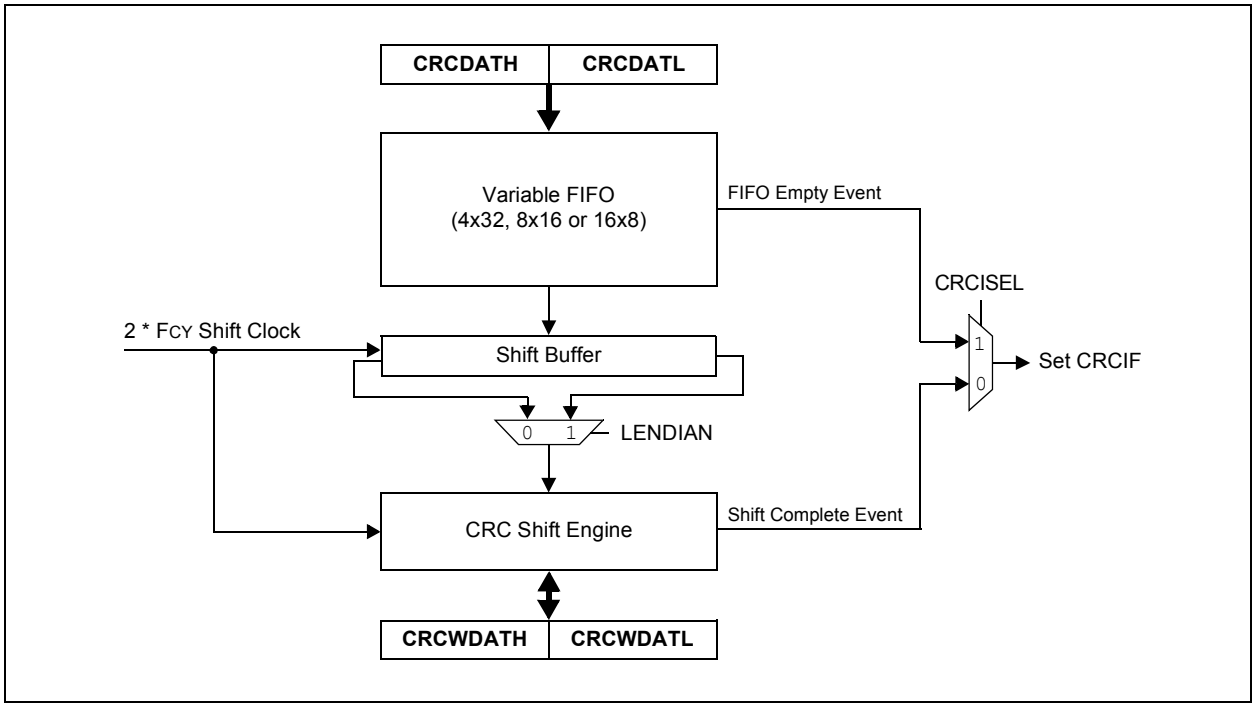
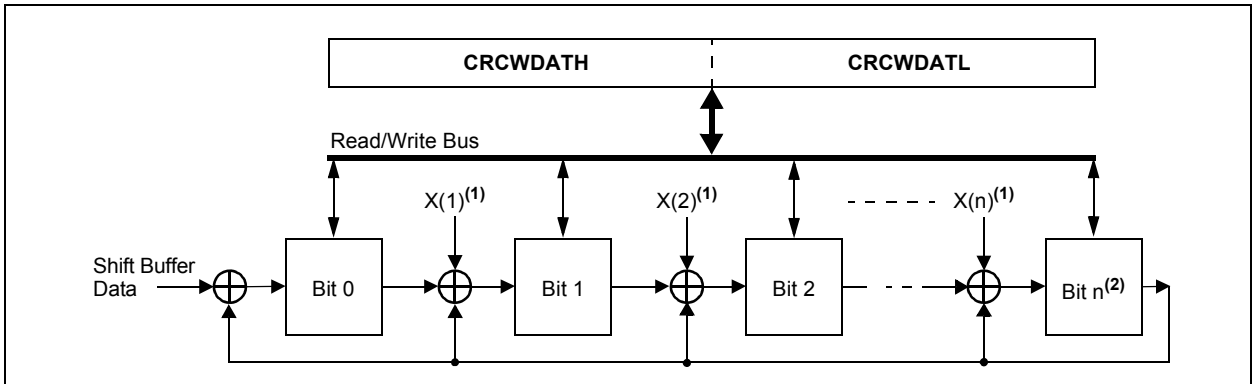
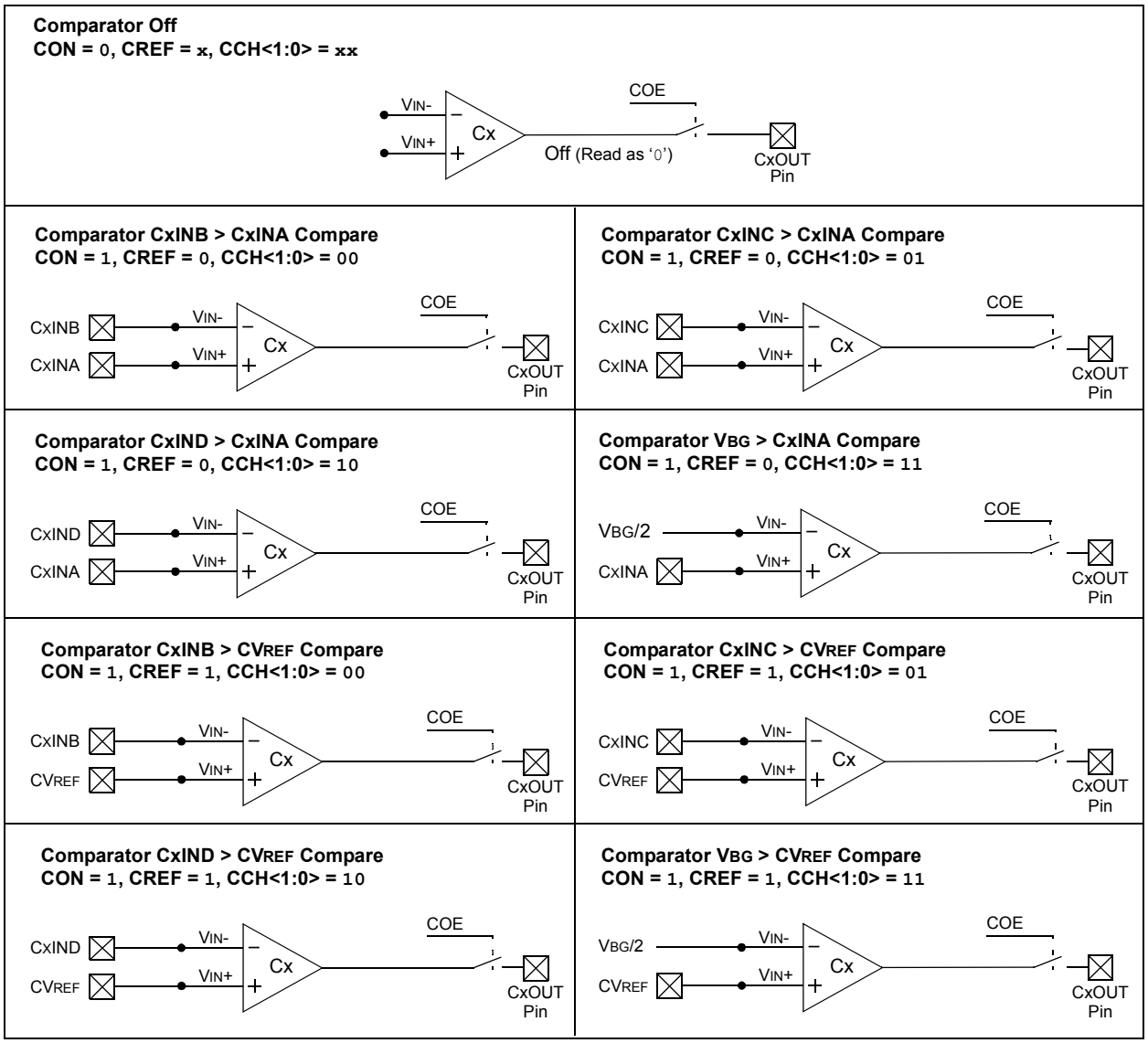


FIGURE 20-2: CRC SHIFT ENGINE DETAIL



Note 1: Each XOR stage of the shift engine is programmable; see text for details.
2: Polynomial Length n is determined by ([PLEN<4:0>] + 1).

FIGURE 23-2: INDIVIDUAL COMPARATOR CONFIGURATIONS



REGISTER 24-1: CVRCON: COMPARATOR VOLTAGE REFERENCE CONTROL REGISTER

U-0	U-0	U-0	U-0	U-0	U-0	U-0	U-0
—	—	—	—	—	—	—	—
bit 15							bit 8

R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0
CVREN	CVROE	CVRSS	CVR4	CVR3	CVR2	CVR1	CVR0
bit 7							bit 0

Legend:			
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as '0'	
-n = Value at POR	'1' = Bit is set	'0' = Bit is cleared	x = Bit is unknown

bit 15-8 **Unimplemented:** Read as '0'

bit 7 **CVREN:** Comparator Voltage Reference Enable bit
1 = CVREF circuit is powered on
0 = CVREF circuit is powered down

bit 6 **CVROE:** Comparator VREF Output Enable bit
1 = CVREF voltage level is output on the CVREF pin
0 = CVREF voltage level is disconnected from the CVREF pin

bit 5 **CVRSS:** Comparator VREF Source Selection bit
1 = Comparator reference source, CVRSRC = VREF+ – VREF-
0 = Comparator reference source, CVRSRC = AVDD – AVSS

bit 4-0 **CVR<4:0>:** Comparator VREF Value Selection 0 ≤ CVR<4:0> ≤ 31 bits
When CVRSS = 1:
CVREF = (VREF-) + (CVR<4:0>/32) • (VREF+ – VREF-)
When CVRSS = 0:
CVREF = (AVSS) + (CVR<4:0>/32) • (AVDD – AVSS)

REGISTER 26-4: FOSC: OSCILLATOR CONFIGURATION REGISTER

R/P-1	R/P-1	R/P-1	R/P-1	R/P-1	R/P-1	R/P-1	R/P-1
FCKSM1	FCKSM0	SOSCSEL	POSCFREQ1	POSCFREQ0	OSCIOFNC	POSCMD1	POSCMD0
bit 7							bit 0

Legend:			
R = Readable bit	P = Programmable bit	U = Unimplemented bit, read as '0'	
-n = Value at POR	'1' = Bit is set	'0' = Bit is cleared	x = Bit is unknown

bit 7-6 **FCKSM<1:0>:** Clock Switching and Fail-Safe Clock Monitor Selection Configuration bits
1x = Clock switching is disabled, Fail-Safe Clock Monitor is disabled
01 = Clock switching is enabled, Fail-Safe Clock Monitor is disabled
00 = Clock switching is enabled, Fail-Safe Clock Monitor is enabled

bit 5 **SOSCSEL:** Secondary Oscillator Power Selection Configuration bit
1 = Secondary oscillator is configured for high-power operation
0 = Secondary oscillator is configured for low-power operation

bit 4-3 **POSCFREQ<1:0>:** Primary Oscillator Frequency Range Configuration bits
11 = Primary oscillator/external clock input frequency is greater than 8 MHz
10 = Primary oscillator/external clock input frequency is between 100 kHz and 8 MHz
01 = Primary oscillator/external clock input frequency is less than 100 kHz
00 = Reserved; do not use

bit 2 **OSCIOFNC:** CLKO Enable Configuration bit
1 = CLKO output signal is active on the OSCO pin; primary oscillator must be disabled or configured for the External Clock mode (EC) for the CLKO to be active (POSCMD<1:0> = 11 or 00)
0 = CLKO output is disabled

bit 1-0 **POSCMD<1:0>:** Primary Oscillator Configuration bits
11 = Primary Oscillator mode is disabled
10 = HS Oscillator mode is selected
01 = XT Oscillator mode is selected
00 = External Clock mode is selected

TABLE 29-6: DC CHARACTERISTICS: OPERATING CURRENT (IDD)

DC CHARACTERISTICS		Standard Operating Conditions: 1.8V to 3.6V PIC24F32KA3XX 2.0V to 5.5V PIC24FV32KA3XX Operating temperature: -40°C ≤ TA ≤ +85°C for Industrial -40°C ≤ TA ≤ +125°C for Extended				
Parameter No.	**Device**	**Typical**	**Max**	**Units**		**Conditions**
IDD Current						
D20	PIC24FV32KA3XX	269	450	µA	2.0V	0.5 MIPS, FOSC = 1 MHz(1)
		465	830	µA	5.0V	
	PIC24F32KA3XX	200	330	µA	1.8V	
		410	750	µA	3.3V	
DC22	PIC24FV32KA3XX	490	—	µA	2.0V	1 MIPS, FOSC = 2 MHz(1)
		880	—	µA	5.0V	
	PIC24F32KA3XX	407	—	µA	1.8V	
		800	—	µA	3.3V	
DC24	PIC24FV32KA3XX	13.0	20.0	mA	5.0V	16 MIPS, FOSC = 32 MHz(1)
	PIC24F32KA3XX	12.0	18.0	mA	3.3V	
DC26	PIC24FV32KA3XX	2.0	—	mA	2.0V	FRC (4 MIPS), FOSC = 8 MHz
		3.5	—	mA	5.0V	
	PIC24F32KA3XX	1.80	—	mA	1.8V	
		3.40	—	mA	3.3V	
DC30	PIC24FV32KA3XX	48.0	250	µA	2.0V	LPRC (15.5 KIPS), FOSC = 31 kHz
		75.0	450	µA	5.0V	
	PIC24F32KA3XX	8.1	28	µA	1.8V	
		13.50	150	µA	3.3V	

Legend: Unshaded rows represent PIC24F32KA3XX devices and shaded rows represent PIC24FV32KA3XX devices.

Note 1: Oscillator is in External Clock mode (FOSCSEL<2:0> = 010, FOSC<1:0> = 00).

TABLE 29-9: DC CHARACTERISTICS: I/O PIN INPUT SPECIFICATIONS

DC CHARACTERISTICS			Standard Operating Conditions: 1.8V to 3.6V PIC24F32KA3XX 2.0V to 5.5V PIC24FV32KA3XX Operating temperature -40°C ≤ TA ≤ +85°C for Industrial -40°C ≤ TA ≤ +125°C for Extended				
Param No.	**Sym**	**Characteristic**	**Min**	**Typ(1)**	**Max**	**Units**	**Conditions**
	VIL	**Input Low Voltage(4)**					
DI10		I/O Pins	VSS	—	0.2 VDD	V	
DI15		$\overline{MCLR}$	VSS	—	0.2 VDD	V	
DI16		OSCI (XT mode)	VSS	—	0.2 VDD	V	
DI17		OSCI (HS mode)	VSS	—	0.2 VDD	V	
DI18		I/O Pins with I2C™ Buffer	VSS	—	0.3 VDD	V	SMBus is disabled
DI19		I/O Pins with SMBus Buffer	VSS	—	0.8	V	SMBus is enabled
	VIH	**Input High Voltage(4)**					
DI20		I/O Pins:					
		with Analog Functions	0.8 VDD	—	VDD	V	
		Digital Only	0.8 VDD	—	VDD	V	
DI25		$\overline{MCLR}$	0.8 VDD	—	VDD	V	
DI26		OSCI (XT mode)	0.7 VDD	—	VDD	V	
DI27		OSCI (HS mode)	0.7 VDD	—	VDD	V	
DI28		I/O Pins with I2C Buffer:					
		with Analog Functions	0.7 VDD	—	VDD	V	
		Digital Only	0.7 VDD	—	VDD	V	
DI29		I/O Pins with SMBus	2.1	—	VDD	V	2.5V ≤ VPIN ≤ VDD
DI30	ICNPU	**CNx Pull-up Current**	50	250	500	µA	VDD = 3.3V, VPIN = VSS
	IIL	**Input Leakage Current(2,3)**					
DI50		I/O Ports	—	0.05	0.1	µA	VSS ≤ VPIN ≤ VDD, Pin at high-impedance
DI55		$\overline{MCLR}$	—	—	0.1	µA	VSS ≤ VPIN ≤ VDD
DI56		OSCI	—	—	5	µA	VSS ≤ VPIN ≤ VDD, XT and HS modes

Note 1: Data in "Typ" column is at 3.3V, +25°C unless otherwise stated. Parameters are for design guidance only and are not tested.

2: The leakage current on the $\overline{MCLR}$ pin is strongly dependent on the applied voltage level. The specified levels represent normal operating conditions. Higher leakage current may be measured at different input voltages.

3: Negative current is defined as current sourced by the pin.

4: Refer to Table 1-3 for I/O pin buffer types.

FIGURE 30-7: TYPICAL AND MAXIMUM IDD vs. TEMPERATURE (FRC MODE)

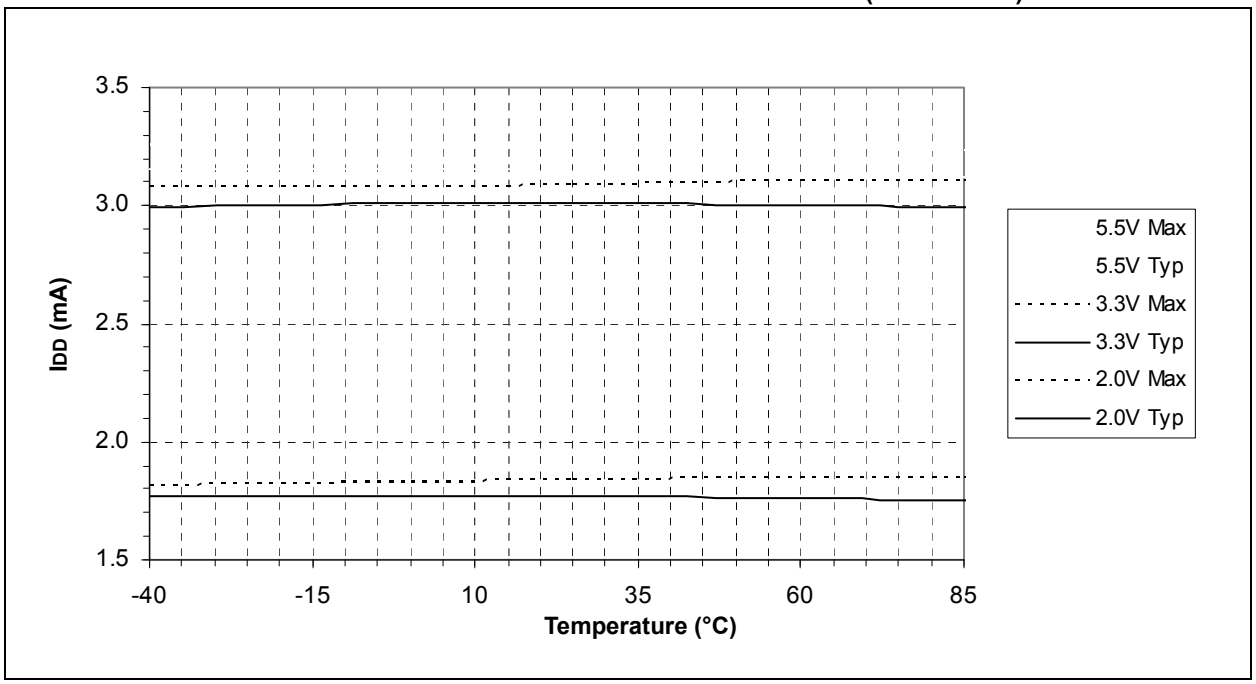


FIGURE 30-8: TYPICAL AND MAXIMUM IIDLE vs. VDD (FRC MODE)

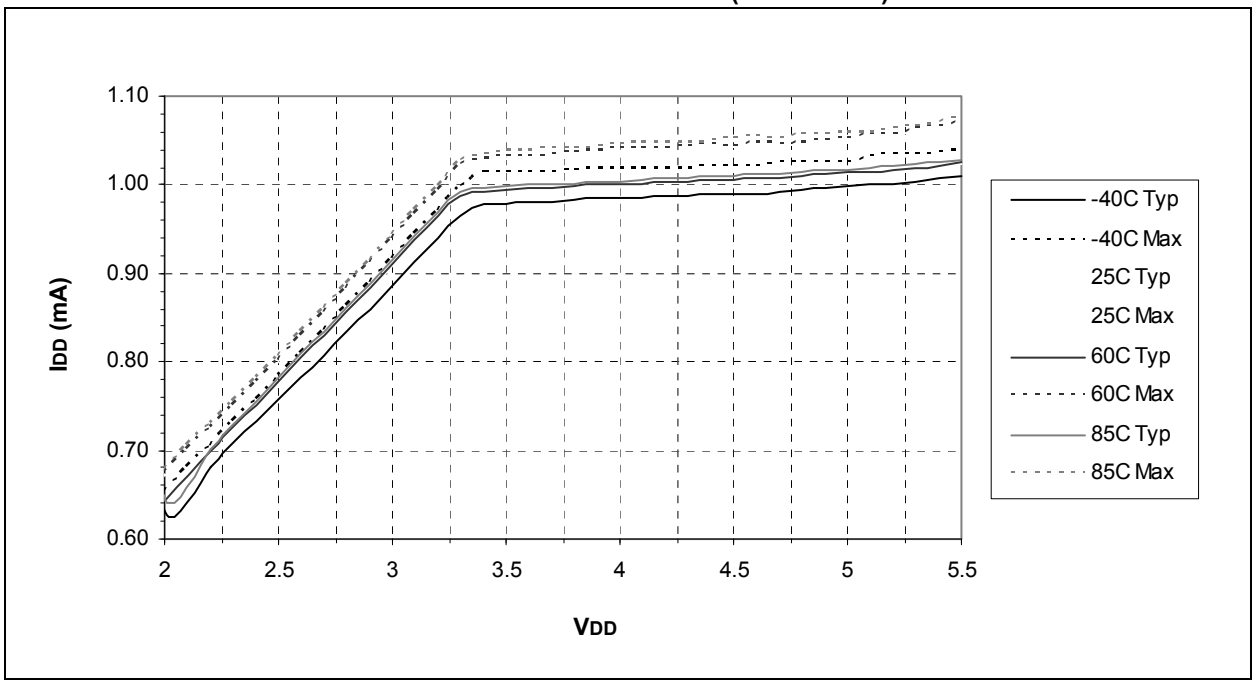


FIGURE 30-10: FRC FREQUENCY ACCURACY vs. VDD

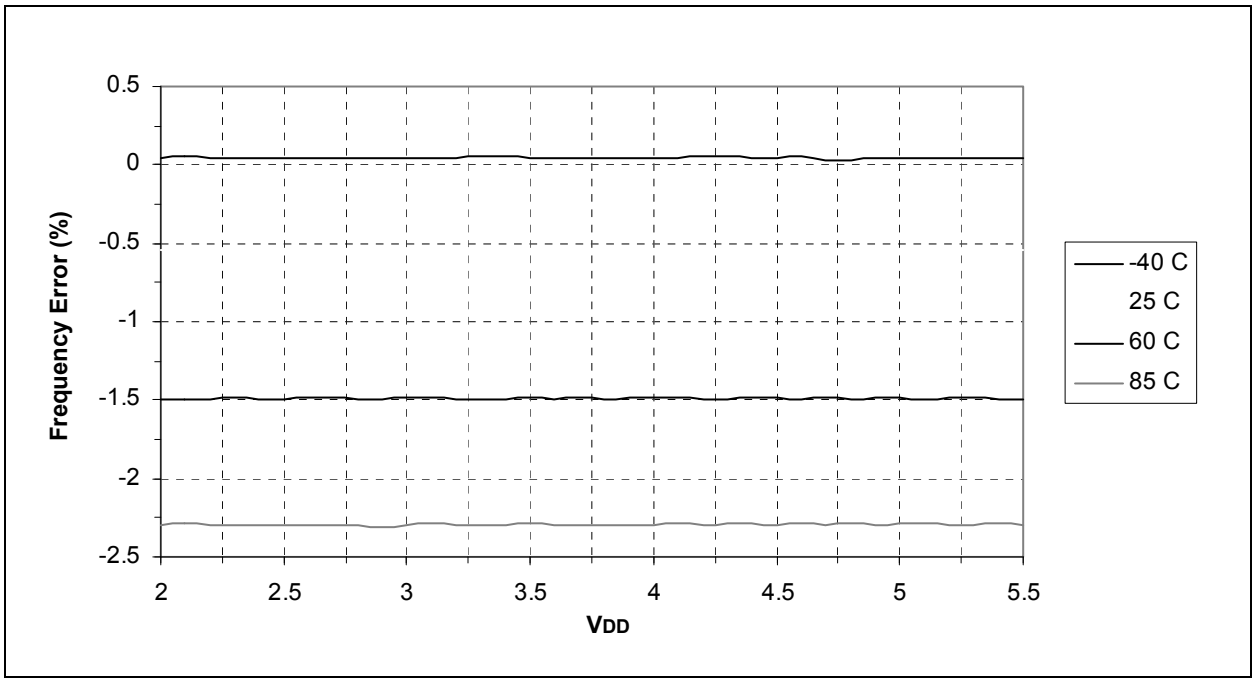


FIGURE 30-11: FRC FREQUENCY ACCURACY vs. TEMPERATURE (2.0V ≤ VDD ≤ 5.5V)

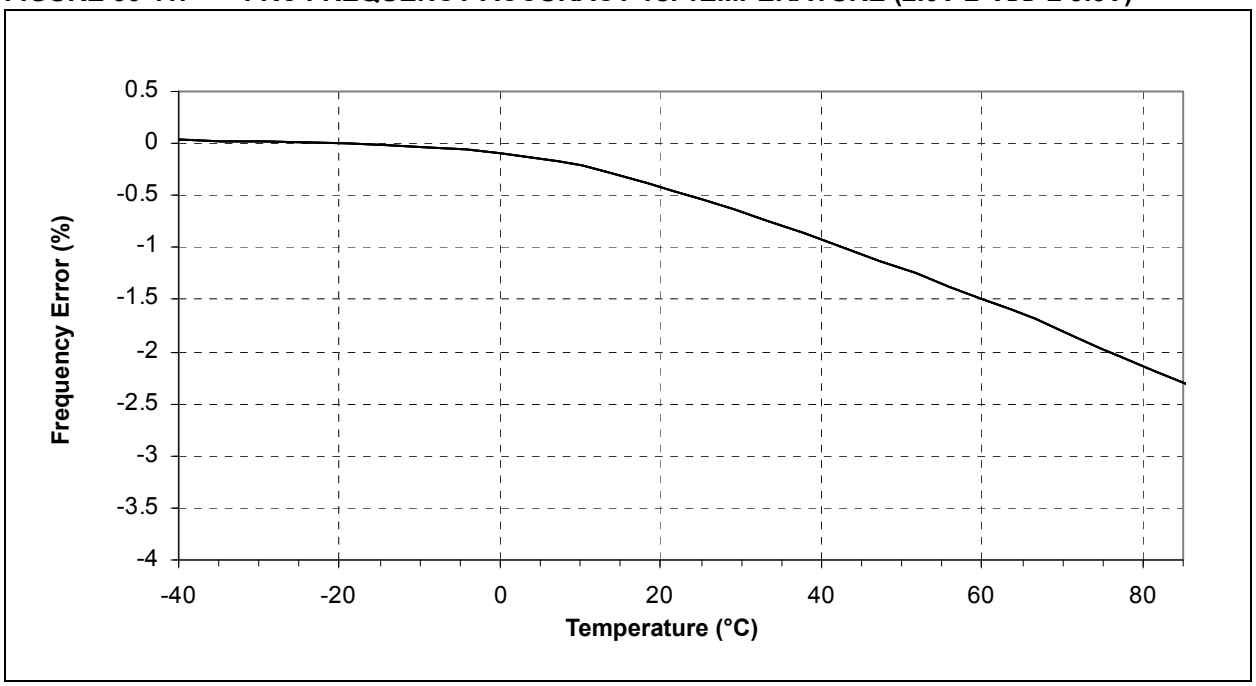


FIGURE 30-14: TYPICAL AND MAXIMUM IPD vs. VDD

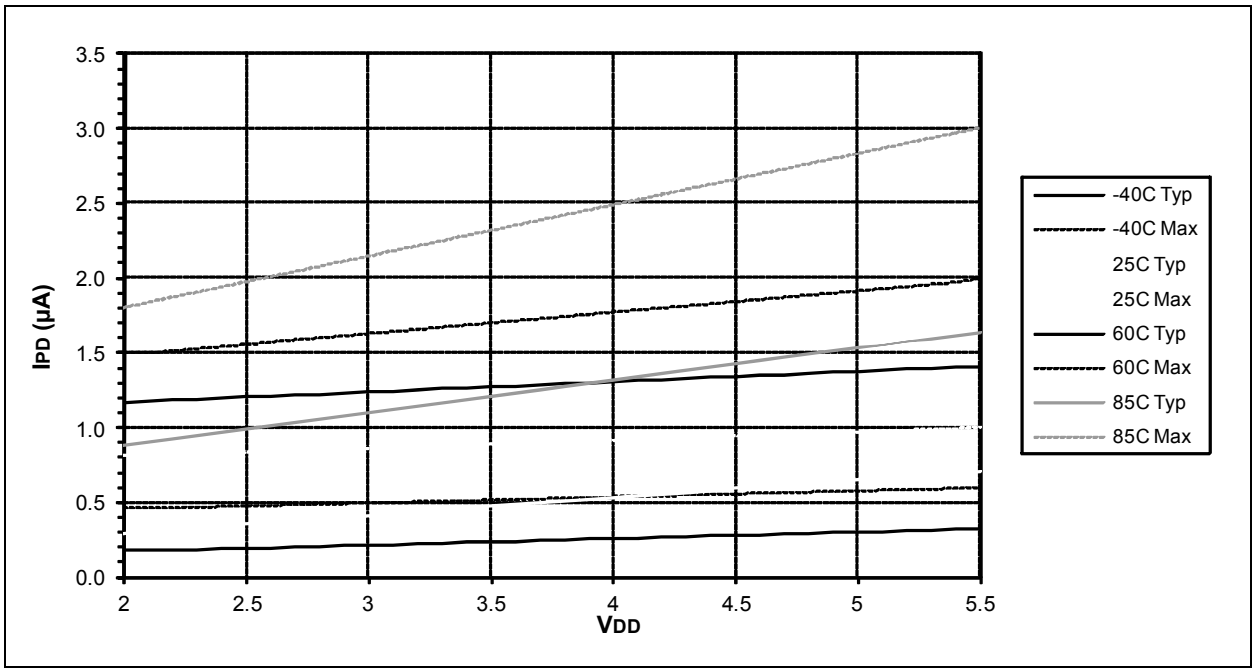


FIGURE 30-15: TYPICAL AND MAXIMUM IPD vs. TEMPERATURE

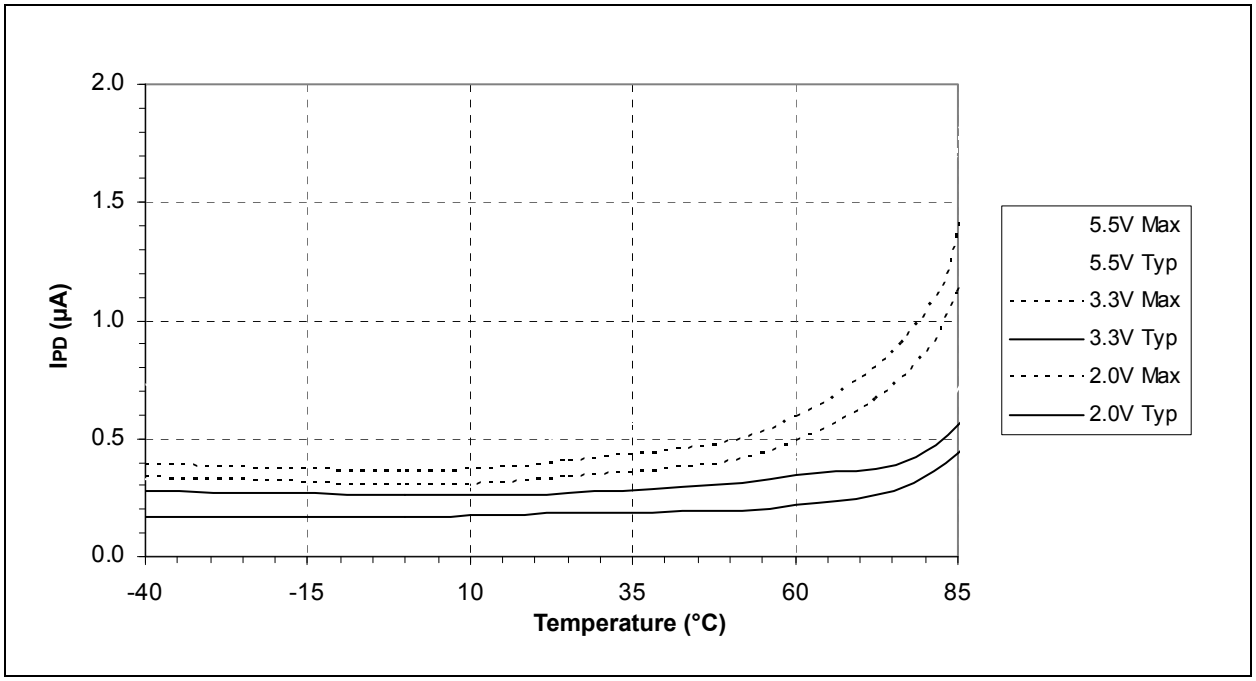


FIGURE 30-36: HLVD TRIP POINT VOLTAGE vs. TEMPERATURE (HLVDL<3:0> = 0000, PIC24F32KA304 FAMILY DEVICES ONLY

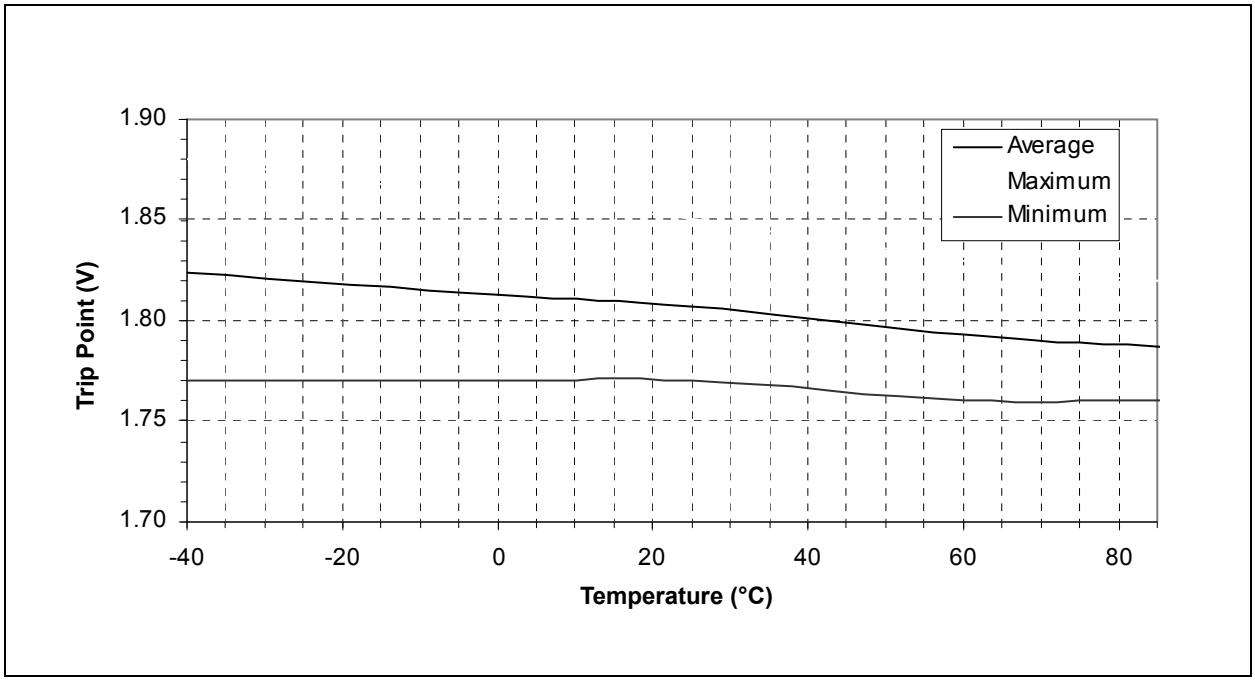


FIGURE 30-37: TEMPERATURE SENSOR DIODE VOLTAGE vs. TEMPERATURE (2.0V ≤ VDD ≤ 5.5V)

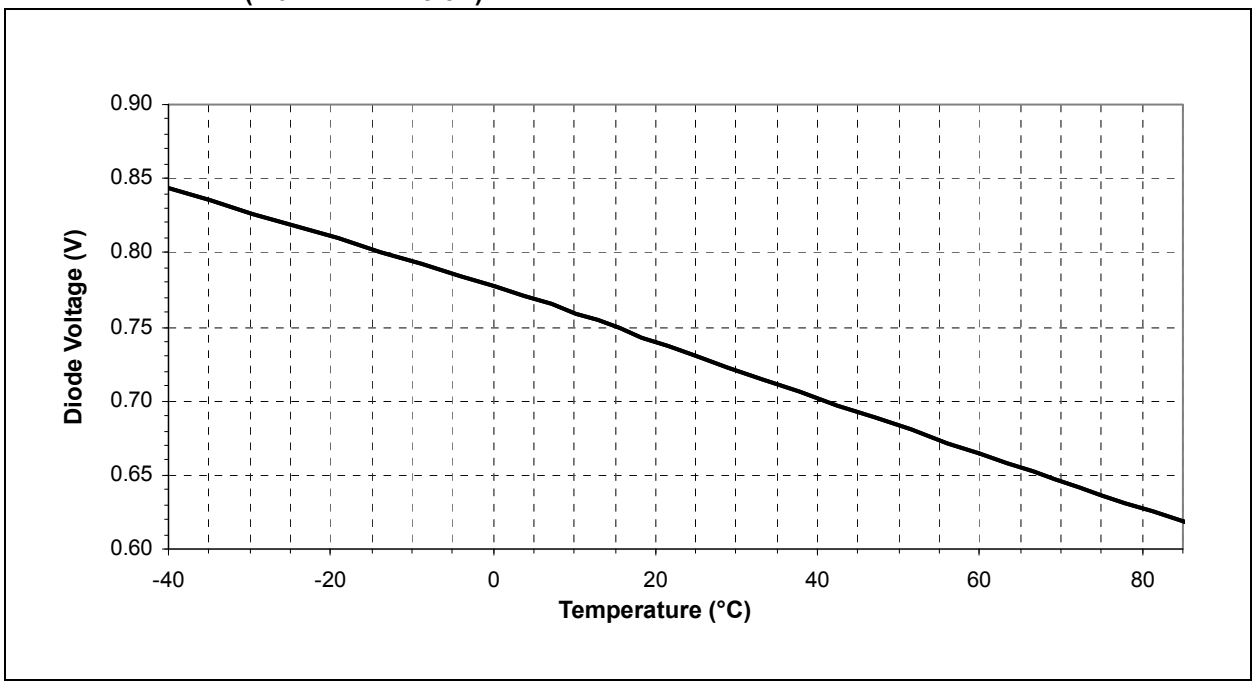


FIGURE 30-44: TYPICAL AND MAXIMUM IPD vs. VDD (DEEP SLEEP MODE)

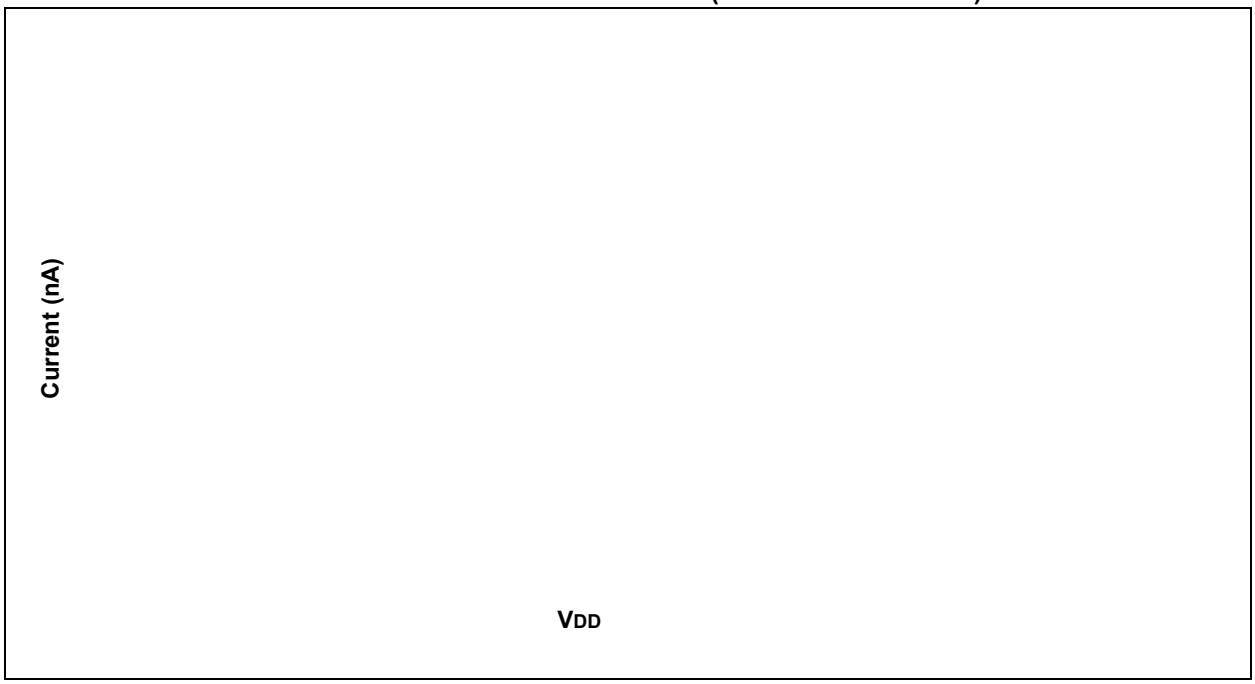
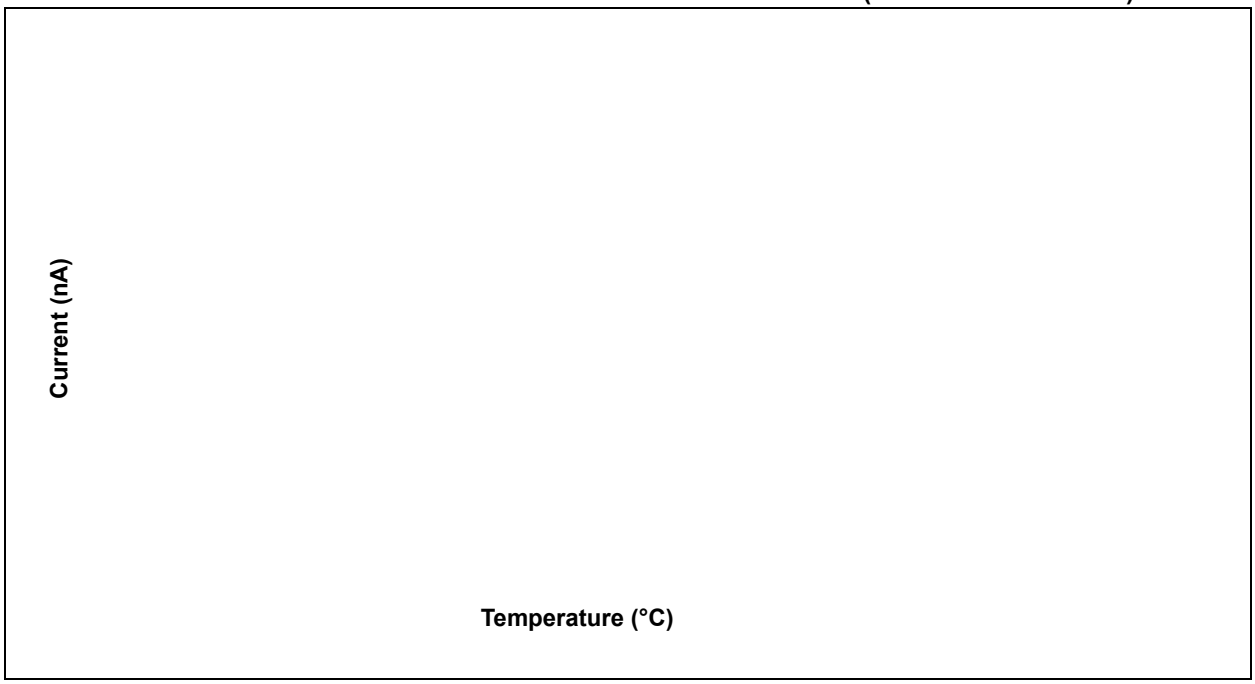
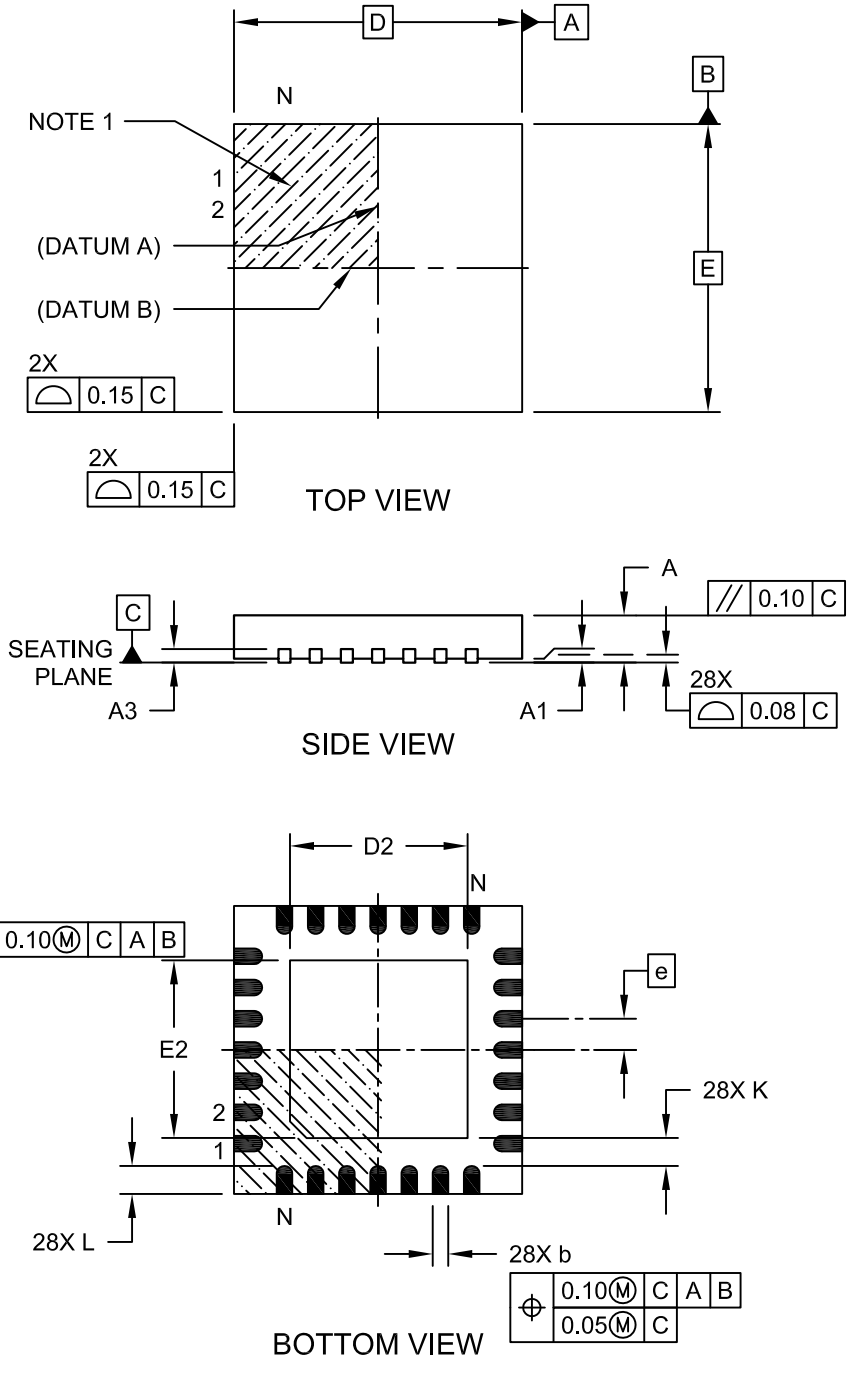


FIGURE 30-45: TYPICAL AND MAXIMUM IPD vs. TEMPERATURE (DEEP SLEEP MODE)



28-Lead Plastic Quad Flat, No Lead Package (ML) - 6x6 mm Body [QFN]
With 0.55 mm Terminal Length

Note:	For the most current package drawings, please see the Microchip Packaging Specification located at http://www.microchip.com/packaging



Microchip Technology Drawing C04-105C Sheet 1 of 2